

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Sang-il KIM	05/16/2008
Tae-gyun KIM	05/16/2008
Tae-woon CHA	05/16/2008
Sang-kwon WEE	05/16/2008
RECEIVING PARTY DATA	
Name:	SAMSUNG Electronics Co., Ltd.
Street Address:	416 Maetan-dong, Yeongtong-gu
City:	Suwon-si, Gyeonggi-do
State/Country:	KOREA, REPUBLIC OF
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12123713
CORRESPONDENCE DATA	
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ATTORNEY DOCKET NUMBER:	401-1141
NAME OF SUBMITTER:	Patrick J. Stanzione
Total Attachments: 1 source=Assignment#page1.tif	

CH \$40.00 12123713

PATENT

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REEL: 020972 FRAME: 0235

U.S. ASSIGNMENT

IN CONSIDERATION of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned Inventor(s) (hereinafter, "ASSIGNOR") by (insert Name(s) & Address(es) of ASSIGNEE(S))

SAMSUNG Electronics Co., Ltd.
416 Maetan-dong, Yeongtong-gu
Suwon-si, Gyeonggi-do
Republic of Korea

(hereinafter, "ASSIGNEE"), the receipt of which is hereby acknowledged, the undersigned ASSIGNOR hereby sells, assigns and transfers to ASSIGNEE the entire and exclusive right, title and interest to the invention entitled

APPARATUS AND METHOD FOR MEASURING THICKNESS OF INK LAYER IN PIXEL

relating to International Patent Application PCT _____/_____ and/or for which application for Letters Patent of the United States was executed on even date herewith or, if not so executed, was:

(a) executed on _____; (Insert date of execution of application, if not concurrent)

(b) filed on _____

Serial No. _____/_____

*** Any registered attorney of Stanzone & Kim, LLP, 919 18th Street, N.W., Washington, D.C. 20006, is hereby authorized to insert in section (b) above the specified data, when known.***

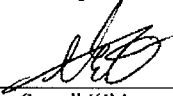

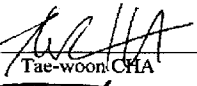

and to said application and all Letters patent(s) of the United States granted on said application and any continuation, division, renewal, substitute, reissue or reexamination application based thereon, for the full term or terms for which the said Letters Patent(s) may be granted and including any extensions thereof (collectively, hereinafter, "said application(s) and Letters Patent(s)").

The ASSIGNOR agree(s), when requested by said ASSIGNEE and without charge to but at the expense of said ASSIGNEE, to do all acts which the ASSIGNEE may deem necessary, desirable or expedient, for securing, maintaining and enforcing protection for said invention, including in the preparation and prosecution of said application(s) and the issuance of said Letters Patent(s), in any interference, reissue, reexamination, or public use proceeding, and in any litigation or other legal proceeding which may arise or be declared in relation to same, such acts to include but not be limited to executing all papers, including separate assignments and declarations, taking all rightful oaths, providing sworn testimony, and obtaining and producing evidence.

IN WITNESS WHEREOF, the undersigned inventor(s) has (have) affixed his/her/their signature(s).

(Typed Name & Signature of Inventor(s))

(Date)

1) 	16/May/2008
Sang-il KIM	
2) 	16/May/2008
Taegyun KIM	
3) 	16/May/2008
Tae-woon CHA	
4) 	16/May/2008
Sang-kwon WEE	